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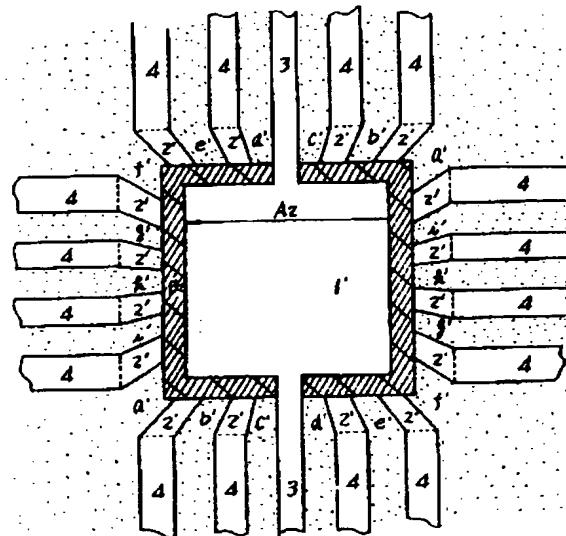
APPLICATION DATE : 09-03-84
APPLICATION NUMBER : 59045252

APPLICANT : NEC CORP;

INVENTOR : OKATOME TETSURO; SOHARA KOUICHI;

INT.CL. : H01L 23/48

TITLE : MANUFACTURE OF LEAD FRAME FOR SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To enable inexpensive alteration in shape by a method wherein outer leads and inner leads continuous to the pellet mount are formed by punching by the use of the same press metal mold; thereafter, a pellet mount suitable for each pellet size is punched by a metal mold corresponding to another pellet size.

CONSTITUTION: In the case of forming lead frames different in size only of islands, first, utilizing a punch used to form the inner leads 2 and the outer leads 4 of the lead frame, parts a'~i' are punched to form inner leads 2' and the outer leads 4. Thereafter, lead frames different in island size can be offered by punching the B₂ part with punches provided individually. Thereby, if many kinds of punches forming islands are prepared, lead frames suitable for pellet sizes can be supplied, and the yield in the assembly process can be largely improved.

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